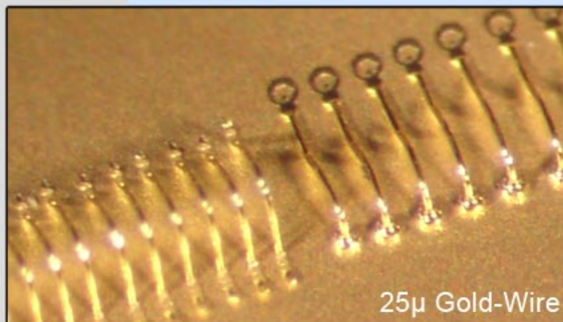
HB16
Wedge and Ball Bonder


25µ Gold-Wire

TFT Display

+ Wedge, Ball and Bump bonding
+ 17µ to 50µ Wire and 25µ x 200µ Ribbon
+ 6,5” TFT Touch panel operation System
+ Deep-access Bond Head 16 mm
+ Bond arm length 165 mm
+ 100 Program storage capacities,
+ Motorised Z Bond Head
+ Motorized Y travel for Step-Back loop control
+ Motorized clamp for precise tail length
+ Motorized 2” Wire Spool Holder
+ USB for backup parameters
+ Loop Profile Programmable
+ Stitch bonding and Bump bonding
+ Semi-auto, Step and Manual Bonding Mode

HB16 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB16 is a bench top size wire bonder, easy to operate and ideal for laboratories.
pilot production runs and small scale production lines.
One Bond head for bonding in Ball/Wedge or Wedge/Wedge bonding mode.
No hardware change necessary. Easy operation with TFT Touch Panel Operator System.
Direct access and simple adjustment to all bond parameters and programs.

Standard	Options
6,5" TFT Touch panel operation System	H10 Zoom Stereo-Microscope Leica S6 20x
90° Bonding Deep-access Bond Head	H21 100 x 100 mm Adjustable height heated work stage
PLL Control Ultrasonic generator	H26 Adjustable height heated work stage surface 60 mm ø
High/Low Ultrasonic Power Selector (1/2 watt)	H29 Adjustable height heated work stage surface 90 mm ø
Large bonding area	H40 Tool Heater and Temperature Controller
Stitch bonding and Bump bonding	with LCD Display
Bond arm length 165 mm	H50 Spot light targeting System
100 Program storage capacities	H51 Manual Z control
USB to store Bonding programs	H60 Bonding tool for Wedge bonding 25µ wire
Built in Dual Fiber Optic illuminator	H61 Bonding tool for Ball Bonding 25µ wir
Built in Heater stage Controller	H70 Gold-Wire 25µ, 60 Meter, 2" Spool
Motorised 2" Wire Spool / Motorised Z & Y	H74 Aluminium -Wire 25µ, 60 Meter, 2" Spool
Semi-automatic, Step and manual bonding	H72 ½ " Wire Spool adapter
Electronic ball size control	H73 Torque Wrench 25 cNm for Bonding Tool
Loop Profile Software	H90 Delivery with installation and 1 day Training

Technical Spezifications

Ultrasonic system	PLL Control 62 kHz transducer
Utrasonic power	0 - 1 watt Low / 0 - 2 watt High output
Bond time	15 - 5000 msec.
Bond force	15 - 110 grams
Bonding Tool	1,58 Dia. X 19 mm length (0,0624" Dia. x 0,75")
Gold wire diameter	17 to 50µ (0,7 to 2 mil)
Aluminium wire diameter	17 to 76µ (0,7 to 3 mil)
Gold ribbon	up to 25 x 200µ
Motorised Wire Spool	50,8 mm (2 inch)
Wire termination	Table tear or Bondhead tear
Wire feed angle	90° for Wire and Ribbon
Motorized Y travel	stepback up to 7 mm (0,27")
Motorized Z travel	15 mm (0,6")
Throat depth	165 mm (6,7")
Fine Table motion	10 mm (0,55 ")
Mouse ratio	6:1 (Option 4:1 , 3:1)
Temperature controller	up to 250°C +/- 1°C
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	680 mm (27")W x 640 mm (25") D x 490 mm (19") H
Weight	Shipping 60 kg Net 45 kg
Industry Standards	CE standards

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Specifications are subject to change without prior notice